

# A New Method to Determine Channel Mobility Model Parameters in Submicron MOSFET's using Measured S-Parameters

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**Abstract** - A new method based on the slope extraction of the total gate charge versus mask gate length from measured S-parameters is developed to determine effective channel mobility model parameters directly from submicron MOSFET's. Since this method does not require a large test device, parasitic capacitance calibration, or the effective channel length measurement, it is simpler and more accurate than traditional methods.

## I. INTRODUCTION

Effective channel mobility ( $\mu_{\text{eff}}$ ) is an essential parameter for the characterization, modeling, and structure design of Si MOSFET's. The gate-voltage dependence of  $\mu_{\text{eff}}$  due to the variation of the transverse electric field becomes crucial information to understand a carrier transport property in the inversion channel layer and to obtain a SPICE MOSFET model for the channel mobility [1]. The value of  $\mu_{\text{eff}}$  is generally extracted at very small  $V_{\text{DS}}$  using the following relation [2]-[5]:

$$\mu_{\text{eff}} = \frac{L_{\text{eff}} I_{\text{DS}}}{W_{\text{eff}} V_{\text{DS}} Q_{\text{in}}} \quad (1)$$

where  $Q_{\text{in}}$  is the inversion channel charge ( $q_{\text{in}}$ ) per unit area,  $W_{\text{eff}}$  is the effective channel width, and  $L_{\text{eff}}$  is the effective channel length.

In order to increase the accuracy of  $L_{\text{eff}}$ , and to neglect the series resistance ( $R_{\text{sd}}$ ) and the parasitic capacitance associated with overlap and fringe components ( $C_{\text{p}}$ ), a very long channel MOSFET is typically used to extract  $\mu_{\text{eff}}$  [2]-[4]. However, the importance of the mobility extraction directly from submicron MOSFET's has been emphasized, and several direct  $\mu_{\text{eff}}$  extraction methods have been reported [5], [6]. However, in the recent method of [5],  $Q_{\text{in}}$  was approximated by the linear equation:  $Q_{\text{in}} = C_{\text{OX}}(V_{\text{GS}} - V_{\text{TH}})$ , yielding

inaccurate results due to the poor approximation around the threshold voltage ( $V_{\text{TH}}$ ) and possible errors for extracting  $C_{\text{OX}}$ . As another approach to determine  $Q_{\text{in}}$ , a low-frequency split C-V method is widely used [2]-[5]. However, a very long-channel test device is still required and mobility extraction errors are generated by bias discrepancy between I-V and C-V measurements [4], [7].

Thus, an effective way to obtain the accurate  $Q_{\text{in}}$  directly from a short channel MOSFET without these errors may utilize S-parameters measured in the range of gigahertz, but the complicated extraction for  $L_{\text{eff}}$  and  $C_{\text{p}}$  is still needed. Therefore, in this paper, we propose a new mobility extraction method using the slope of the total gate charge ( $q_{\text{gt}}$ ) vs. the mask gate length ( $L_{\text{msk}}$ ).

## II. MOBILITY EXTRACTION METHOD

The total dc resistance is expressed at very small  $V_{\text{DS}}$  as follows [5], [8]:

$$R_{\text{tot}} = \frac{V_{\text{DS}}}{I_{\text{DS}}} = A L_{\text{msk}} + B \quad (2)$$

$$A = \frac{1}{\mu_{\text{eff}} W_{\text{eff}} Q_{\text{in}}} \quad (3)$$

$$B = R_{\text{sd}} - A \Delta L \quad (4)$$

where  $\Delta L (= L_{\text{msk}} - L_{\text{eff}})$  is the channel length reduction. Here, A and B are the slope and y-intercept of the  $R_{\text{tot}}$  versus  $L_{\text{msk}}$  at a fixed  $V_{\text{GS}} - V_{\text{TH}}$ , respectively. As  $L_{\text{msk}}$  varies, the threshold voltage is slightly shifted in short-channel MOSFETs. This short channel effect can be taken into account by fixing  $V_{\text{GS}} - V_{\text{TH}}$  instead of  $V_{\text{GS}}$  in (3) [8].

Rearranging (3) and using  $q_{\text{in}} = Q_{\text{in}} W_{\text{eff}} L_{\text{eff}}$ , we obtain the

following equation [5]:

$$\mu_{\text{eff}} = \frac{1}{A W_{\text{eff}} Q_{\text{in}}} = \frac{L_{\text{eff}}}{A Q_{\text{in}}} \quad (5)$$

Equation (5) does not suffer serious extraction problem related to the gate voltage dependence of  $R_{\text{sd}}$ , because it is not function of  $B$ . Because of this advantage, a total resistance slope-based method using (5) has recently been proposed to determine  $\mu_{\text{eff}}$  [5]. However, the determination of  $L_{\text{eff}}$  is still required and inaccurate extraction of  $Q_{\text{in}}$  may be induced in submicron MOSFET's.

The value of  $q_{\text{in}}$  in (5) is determined by integrating the gate-channel capacitance ( $C_{\text{GC}}$ ):

$$q_{\text{in}} = \int_0^{V_{\text{GS}}-V_{\text{TH}}} C_{\text{GC}}(V') dV' \quad (6)$$

The values of  $C_{\text{GC}}$  can be measured at zero  $V_{\text{DS}}$  using a C-V meter in the range of megahertz [2]-[5], but large errors associated with unavoidable pad capacitances [7], poor measurement sensitivity for low capacitance values, and difficult  $L_{\text{eff}}$  determination may occur in submicron devices. To eliminate these problems, measured S-parameters are used to obtain  $C_{\text{GC}}$  data in this work, because the de-embedding or calibration of parasitic pad parasitics is possible in GHz S-parameter measurements.

Because series resistance components in a small-signal MOSFET model [9] are omitted in the very low range of gigahertz, the gate capacitance as a function of  $V_{\text{GS}}-V_{\text{TH}}$  can be measured using the following imaginary term of  $Y_{11}$ -parameter converted from S-parameters:

$$C_{\text{G}}(V_{\text{GS}}-V_{\text{TH}}) = C_{\text{GS}}+C_{\text{GD}} = \frac{1}{\omega} \text{Imag}(Y_{11}) \quad (7)$$

The measured gate capacitance for all devices with different  $L_{\text{msk}}$  consists of the following components:

$$C_{\text{G}}(V_{\text{GS}}-V_{\text{TH}}) = C_{\text{P}} + C_{\text{GC}} \quad (8)$$

In order to obtain  $q_{\text{in}}$  accurately,  $C_{\text{P}}$  should be subtracted from  $C_{\text{G}}$ . However, the accurate determination of  $C_{\text{P}}$  is very difficult in submicron CMOS technology. In addition, for obtaining  $\mu_{\text{eff}}$  using (5), the extra knowledge for  $L_{\text{eff}}$  that strongly depends on extraction methods [10] and gate voltage [11] is still required.

Therefore, in this paper, the following new equation is proposed to avoid this difficult  $C_{\text{P}}$  and  $L_{\text{eff}}$  extraction. The

From (5), we obtain the following equation for the measured total gate charge:

$$\begin{aligned} q_{\text{gt}} &= \int_0^{V_{\text{GS}}-V_{\text{TH}}} C_{\text{GC}}(V') dV' = C_{\text{P}}(V_{\text{GS}}-V_{\text{TH}}) + q_{\text{in}} \\ &= C_{\text{P}}(V_{\text{GS}}-V_{\text{TH}}) + \frac{L_{\text{msk}} - \Delta L}{A \mu_{\text{eff}}} = C L_{\text{msk}} + D \end{aligned} \quad (9)$$

where  $C$  and  $D$  are the slope and y-intercept of the extracted  $q_{\text{gt}}$  versus  $L_{\text{msk}}$  at a fixed  $V_{\text{GS}}-V_{\text{TH}}$ , respectively. Here, the slope  $C$  is independent of  $L_{\text{msk}}$ , because the effect of the threshold voltage shift disappears by fixing  $V_{\text{GS}}-V_{\text{TH}}$  for different  $L_{\text{msk}}$ .

From (9), we easily extract  $\mu_{\text{eff}}$  in the following simple expression :

$$\mu_{\text{eff}} = \frac{1}{AC} \quad (10)$$

This inverse-slope-product equation is not affected by errors of  $D$  generated in the extraction of  $C_{\text{P}}$  and  $L_{\text{eff}}$ , thus making the new method more reliable than the previously reported method [5] using (5).

### III. RESULTS

Under common source-bulk configuration, S-parameters were measured in the gigahertz range on n-MOSFET's of  $4 \times 10 \mu\text{m}$  gate width with  $L_{\text{msk}}$  of 0.8, 1.0, and 1.2  $\mu\text{m}$  [12], and pad and interconnection de-embedding was carried out using "open" and "short" test patterns [13]. In this case, the same bias of  $V_{\text{DS}} = 50\text{mV}$  as I-V measurements is applied to eliminate bias discrepancy errors [4].

The measured data and their best fit lines of  $R_{\text{tot}}$  vs.  $L_{\text{msk}}$  are plotted with varying  $V_{\text{GS}}-V_{\text{TH}}$  in Fig. 1, and these data are straight lines at fixed  $V_{\text{GS}}-V_{\text{TH}}$ . This indicates the independence of  $A$  on  $L_{\text{msk}}$ . Using (9), the measured values of  $q_{\text{gt}}$  are determined by integrating  $C_{\text{GC}}$  values obtained from (7) with respect to  $V_{\text{GS}}-V_{\text{TH}}$ . These  $q_{\text{gt}}$  data are plotted as a function of  $L_{\text{msk}}$  at several fixed bias points of  $V_{\text{GS}} - V_{\text{TH}}$ , and the good linearity is observed in Fig. 2. The plot of  $q_{\text{gt}}$  versus  $V_{\text{GS}} - V_{\text{TH}}$  is also shown in Fig. 3 for various  $L_{\text{msk}}$ . As expected by the theory, the  $q_{\text{gt}}$  data are linearly proportional to  $V_{\text{GS}}-V_{\text{TH}}$ . Fig. 4 shows slopes  $A$  and  $C$  extracted from best fit lines in Figs. 1 and 2, respectively. By substituting the slopes into (10), the gate-voltage dependence of  $\mu_{\text{eff}}$  is accurately extracted from this new method in Fig. 5.

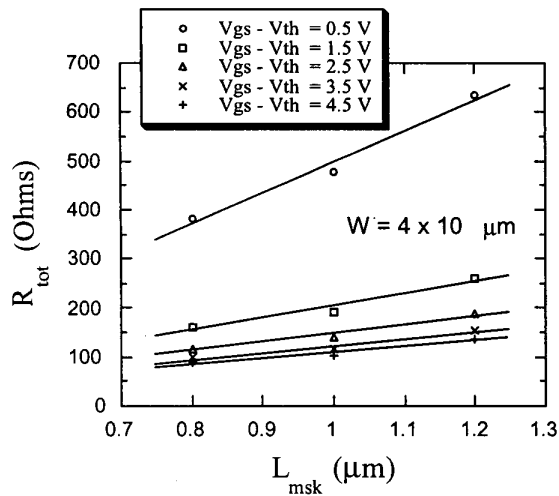


Fig. 1. The measured data and their best fit lines of  $R_{tot}$  for different  $V_{GS} - V_{TH}$  as a function of  $L_{msk}$  at  $V_{DS} = 50mV$ .

A gate-voltage dependent curve of  $\mu_{eff}$  is modeled by the SPICE expression:

$$\mu_{eff} = \frac{U_0}{1 + U_A \left[ \frac{V_{GS} - V_{TH}}{T_{OX}} \right] + U_B \left[ \frac{V_{GS} - V_{TH}}{T_{OX}} \right]^2} \quad (11)$$

By performing the best curve-fit of (11) to extracted  $\mu_{eff}$ , it is extracted that  $U_0 = 463cm^2/Vs$ ,  $U_A/T_{OX} = 0.055 V^{-1}$ , and  $U_B/T_{OX}^2 = 0.032 V^{-2}$ . This modeled curve of  $\mu_{eff}$  agrees well with extracted data as shown in Fig. 5.

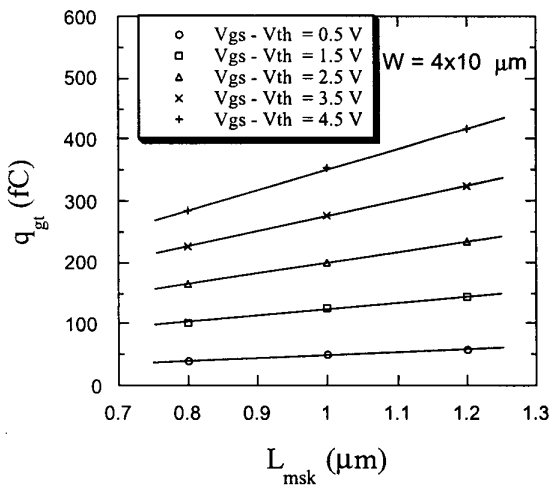


Fig. 2. The extracted data and their best fit lines of the total gate charge  $q_{gt}$  for various  $V_{GS} - V_{TH}$  as a function of  $L_{msk}$  at  $V_{DS} = 50mV$ .

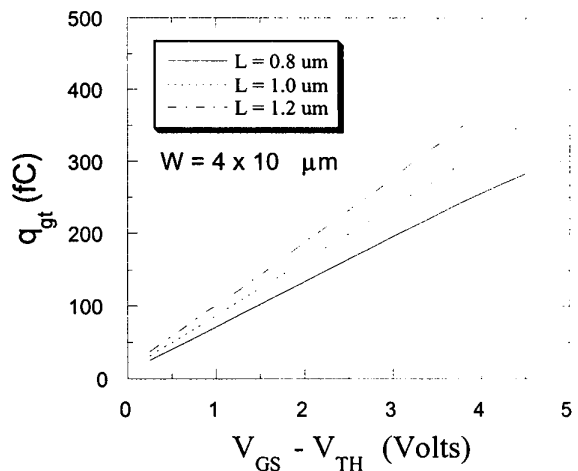


Fig. 3. The extracted data of  $q_{gt}$  as a function of  $V_{GS} - V_{TH}$  for various  $L_{msk}$  at  $V_{DS} = 50mV$ .

#### IV. CONCLUSIONS

We propose a new method for determining  $\mu_{eff}$  directly from submicron MOSFET's, using the slope information of  $q_{gt}$  versus  $L_{msk}$  plot obtained from the measured S-parameters. Unlike conventional approaches, a very long-channel test device or the extra determination of  $C_P$  and  $L_{eff}$  is not required to extract the  $\mu_{eff}$ , thus making the new method simpler and more accurate. The SPICE mobility model curve extracted from a simple curve-fit process agrees well with measured data.

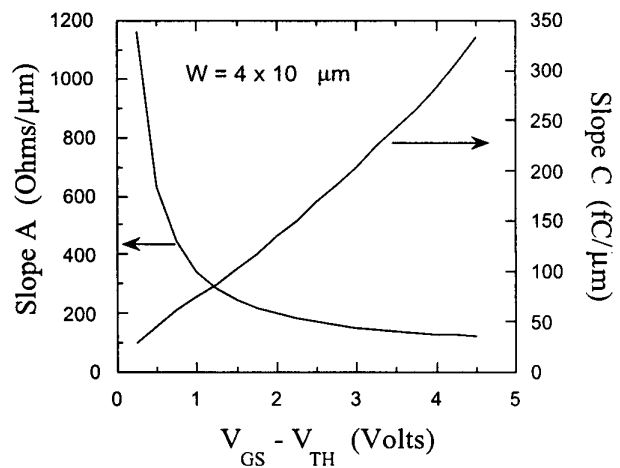


Fig. 4. The extracted slopes A and C as a function of  $V_{GS} - V_{TH}$ .

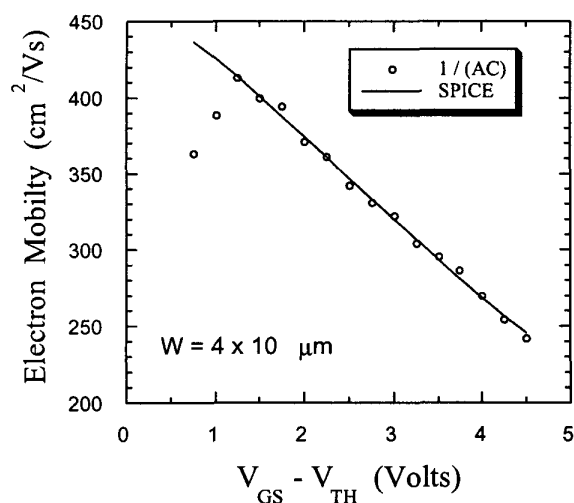


Fig. 5. The extracted  $\mu_{\text{eff}}$  data from the new method using (10) and their fitted SPICE curve using (11).

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#### REFERENCES

- [1] P. Antognetti and G. Massobro, *Semiconductor device modeling with SPICE*, New York: McGraw-Hill, 1991.
- [2] C. G. Sodini, T. W. Ekstedt, and J. L. Moll, "Charge accumulation and mobility in thin dielectric MOS transistors," *Solid-State Electron.*, vol. 25, pp. 833-841, Sept. 1982.
- [3] C.-L. Huang and G. Sh. Gildenblat, "Measurements and Modeling of the n-channel MOSFET inversion layer mobility and device characteristics in the temperature range 60-300 K," *IEEE Trans. Electron Device*, vol. 37, pp. 1289-1300, May 1990.
- [4] C.-L. Huang, J. V. Faricelli, and N. D. Arora, "A new technique for measuring MOSFET inversion layer mobility," *IEEE Trans. Electron Device*, vol. 40, pp. 1134-1139, June 1993.
- [5] G. Niu, J. D. Cressler, S. J. Mathew, and S. Subbanna, "A total resistance slope-based effective channel mobility extraction method for deep submicrometer CMOS technology," *IEEE Trans. Electron Device*, vol. 46, pp. 1912-1914, Sept. 1999.
- [6] H. J. Wildau, H. Bernt, D. Friedrich, W. Seifert, P. Staudt-Fischbach, H. G. Wagemann, and W. Windbracke, "The inversion layer of subhalf-micrometer n-channel and p-channel MOSFET's in the temperature range 208-403 K," *IEEE Trans. Electron Device*, vol. 40, pp. 2318-2325, Dec. 1993.
- [7] J. Banqueri, J. A. Lopez-Villanueva, F. Gamiz, J. E. Carceller, E. Lora-Tamayo, and M. Lozano, "A procedure for the determination of the effective mobility in an N-MOSFET in the moderate inversion region," *Solid-State Electron.*, vol. 39, pp. 875-883, June 1996.
- [8] S. E. Laux., "Accuracy of an effective channel length/external resistance extraction algorithm for MOSFET's," *IEEE Trans. Electron Devices.*, vol. ED-31, pp. 1245-1251, Sept. 1984.
- [9] S. Lee, H. K. Yu, C. S. Kim, J. G. Koo, and K. S. Nam, "A novel approach to extracting small-signal model parameters of silicon MOSFET's," *IEEE Microwave and Guided Wave Lett.*, vol. 7, pp. 75-77, March 1997.
- [10] J. Latif, A. Ortiz-Conde, J. J. Liou, and F. J. Garcia Sanchez, "A study of the validity of capacitance-based method for extracting the effective channel length of MOSFET's," *IEEE Trans. Electron Devices.*, vol. 44, pp. 340-343, Feb. 1997.
- [11] G. J. Hu, C. Chang, and Y.-T. Chia, "Gate-voltage-dependent effective channel length and series resistance of LDD MOSFET's," *IEEE Trans. Electron Devices.*, vol. 34, pp. 2469-2475, 1987.
- [12] C. S. Kim, H. K. Yu, H. Cho, S. Lee, and K. S. Nam, "CMOS layout and bias optimization for RF IC design applications in *IEEE MTT-S Int. Microwave Symp. Dig.*, pp. 945-948, 1997.
- [13] S. Lee, "Effects of pad and interconnection parasitics on forward transit time in HBTs," *IEEE Trans. Electron Devices*, vol. 46, pp. 275-280, Feb. 1999.